



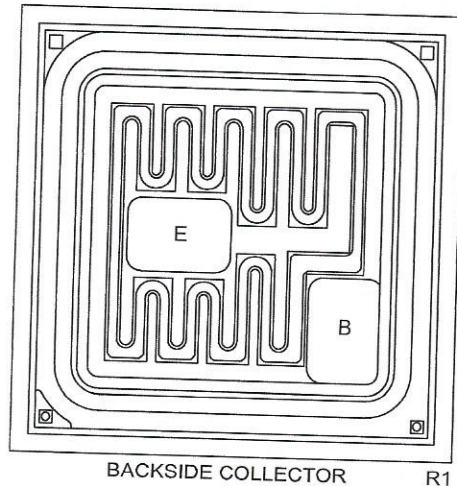
Sierra Components, Inc.

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PROCESS DETAILS

Process	EPITAXIAL PLANAR
Die Size	22 x 22 MILS
Die Thickness	7.1 MILS
Base Bonding Pad Area	5.7 x 3.9 MILS
Emitter Bonding Pad Area	5.3 x 3.9 MILS
Top Side Metalization	Al - 30,000Å
Back Side Metalization	Au - 18,000Å

GEOMETRY



GROSS DIE PER 4 INCH WAFER

23,048

PRINCIPAL DEVICE TYPES

MPSA05
MPSA06

APPROVED BY: MG

DIE SIZE: 22 X 22 Mils

DATE: 11/16/16

MFG: Central Semi

THICKNESS: 7.1 Mils

P/N: MPSA06